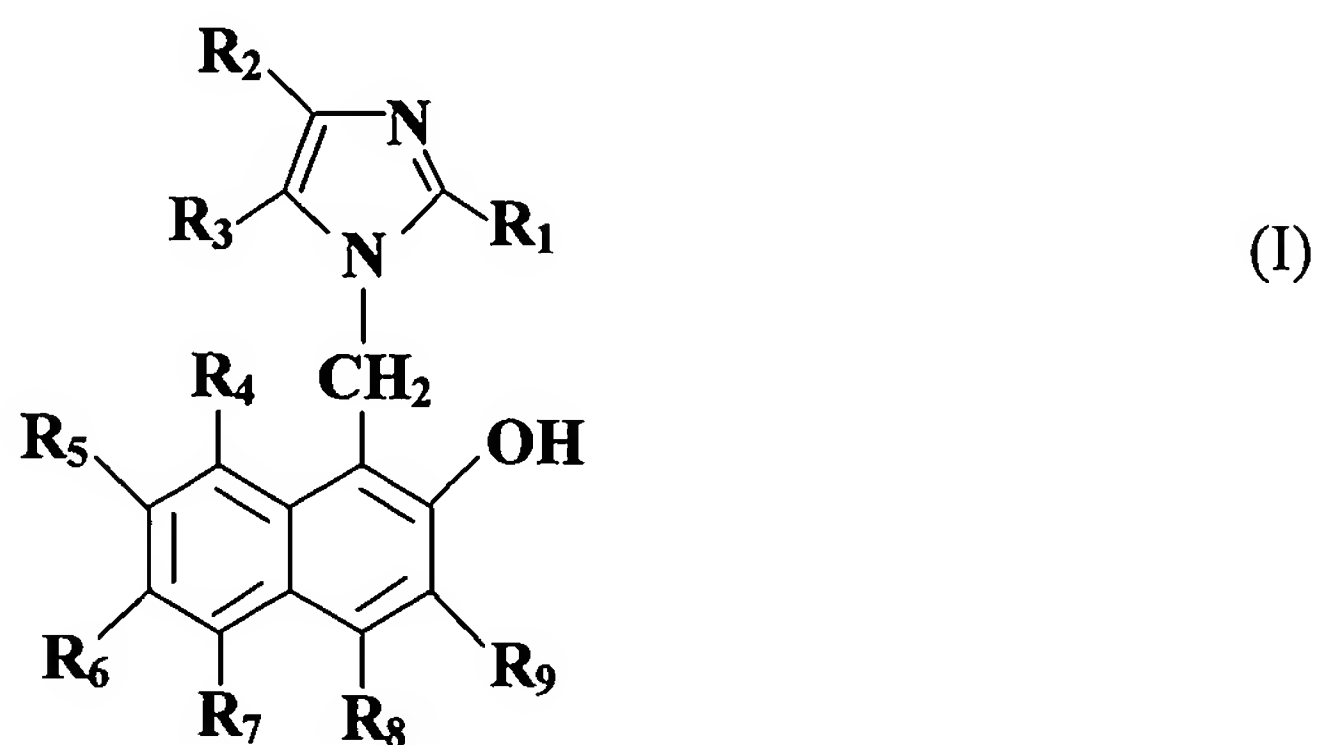


Amendments to the Claims

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claim 1 (currently amended). Composition comprising as component A) a 1-imidazolylmethyl-substituted 2-naphthol compound of the general formula (I)



where

R₁, R₂, and R₃ each independently of one another are H; C₁₋₁₇ alkyl; C₃₋₁₂ cycloalkyl, optionally substituted by C₁₋₄ alkyl groups; C₄₋₂₀ cycloalkyl-alkyl, optionally substituted by C₁₋₄ alkyl groups; C₆₋₁₀ aryl, optionally substituted by 1-3 C₁₋₄ alkyl groups; C₇₋₁₅ phenylalkyl, optionally substituted by 1-3 C₁₋₄ alkyl groups; C₃₋₁₇ alkenyl; C₃₋₁₂ alkynyl; or aromatic or aliphatic C₃₋₁₂ acyl;

R₄, R₅, R₆, R₇, R₈ and R₉ each independently of one another are H; C₁₋₁₂ alkyl; C₃₋₁₂ cycloalkyl, optionally substituted by C₁₋₄ alkyl groups; C₄₋₂₀ cycloalkyl-alkyl, optionally substituted by C₁₋₄ alkyl groups; C₆₋₁₀ aryl, optionally substituted by 1-3 C₁₋₄ alkyl

groups; C₇₋₁₅ phenylalkyl, optionally substituted by 1-3 C₁₋₄ alkyl groups; C₃₋₁₇ alkenyl; C₃₋₁₂ alkynyl; C₁₋₁₂ alkoxy; or OH; and

as component B) a phenol which is liquid at room temperature, with a ~~the~~ weight ratio of component A) to component B) being from 10:90 to 80:20.

Claim 2 (currently amended). Composition according to Claim 1, ~~comprising as component A) a compound in which the radicals~~ wherein R₁, R₂ and R₃ each independently of one another are H; C₁₋₁₂ alkyl; phenyl; or C₇₋₁₅ phenylalkyl, optionally substituted by 1-3 C₁₋₄ alkyl groups.

Claim 3 (currently amended). Composition according to Claim 2, ~~comprising as component A) a compound where~~ wherein R₂ and R₃ are each H; and R₁ is C₁₋₁₂ alkyl; phenyl; or C₇₋₁₅ phenylalkyl, optionally substituted by 1-3 C₁₋₄ alkyl groups.

Claim 4 (currently amended). Composition according to Claim 3, ~~comprising as component A) a compound of the general formula (I) in which the radicals~~ wherein R₂₋₉ are a hydrogen atom and ~~the radical~~ R₁ is C₁₋₄ alkyl, or phenyl, optionally substituted by 1-3 C₁₋₄ alkyl groups.

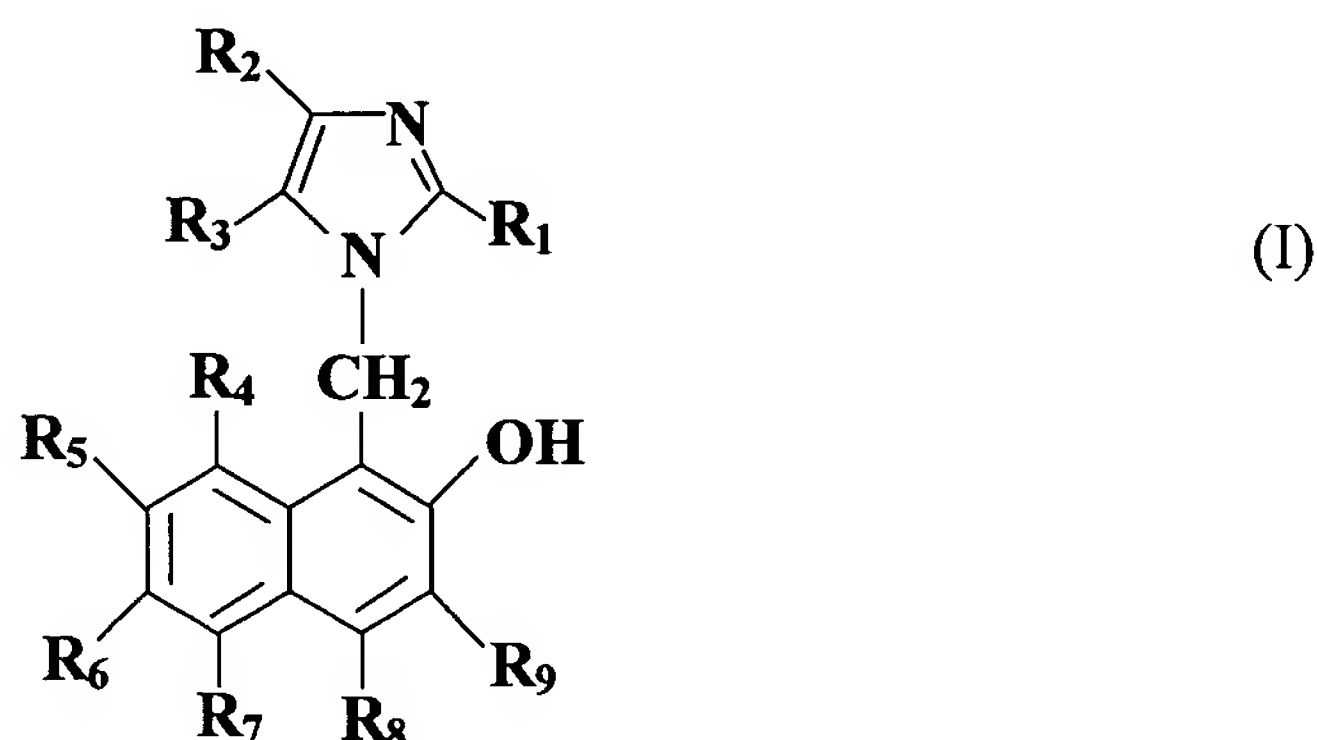
Claim 5 (currently amended). Composition according to Claim 1, ~~characterized in that as~~ wherein component B) is 1,4-n-pentyl-, -n-hexyl-, -n-heptyl-, -n-octyl-, -n-nonyl-, -n-decylphenol, or O,O'-diallyl-bisphenol A ~~is used~~.

Claim 6 (currently amended). Composition according to Claim 1, characterized in that the weight ratio of component A) to component B) is from 20:80 to 70:30, ~~preferably from 25:75 to 50:50~~.

Claim 7 (cancelled).

Claim 8 (currently amended). Curable composition comprising:

- a) an epoxy resin whose epoxide content is from 0.1 to 11 epoxide equivalents/kg;
- b) from 5 to 40 parts by weight, based on the total weight of the curable overall composition of components a) to d), of a composition according to claim 1, comprising a 1-imidazolylmethyl-substituted 2-naphthol compound of the general formula (I)



where

R₁, R₂, and R₃ each independently of one another are H; C₁₋₁₇ alkyl; C₃₋₁₂ cycloalkyl, optionally substituted by C₁₋₄ alkyl groups; C₄₋₂₀ cycloalkyl-alkyl, optionally substituted by C₁₋₄ alkyl groups; C₆₋₁₀ aryl, optionally substituted by 1-3 C₁₋₄ alkyl groups; C₇₋₁₅ phenylalkyl, optionally substituted by 1-3 C₁₋₄ alkyl groups; C₃₋₁₇ alkenyl; C₃₋₁₂ alkynyl; or aromatic or aliphatic C₃₋₁₂ acyl;

R₄, R₅, R₆, R₇, R₈ and R₉ each independently of one another are H; C₁₋₁₂ alkyl; C₃₋₁₂ cycloalkyl, optionally substituted by C₁₋₄ alkyl groups; C₄₋₂₀ cycloalkyl-alkyl, optionally substituted by C₁₋₄ alkyl groups; C₆₋₁₀ aryl, optionally substituted by 1-3 C₁₋₄ alkyl groups; C₇₋₁₅ phenylalkyl, optionally substituted by 1-3 C₁₋₄ alkyl groups; C₃₋₁₇ alkenyl; C₃₋₁₂ alkynyl; C₁₋₁₂ alkoxy; or OH; and

a phenol which is liquid at room temperature, the weight ratio of the 1-imidazolymethyl-substituted 2-naphthol compound to phenol being from 10:90 to 80:20;

- c) a curing agent for the epoxy ~~epoxide~~ resin ~~calculated such that per epoxide group there are from~~ having from 0.5 to 1.5 functional groups per epoxide group of the ~~curing agent~~; and optionally
- d) one or more additives ~~an additive customary in epoxy resin technology.~~

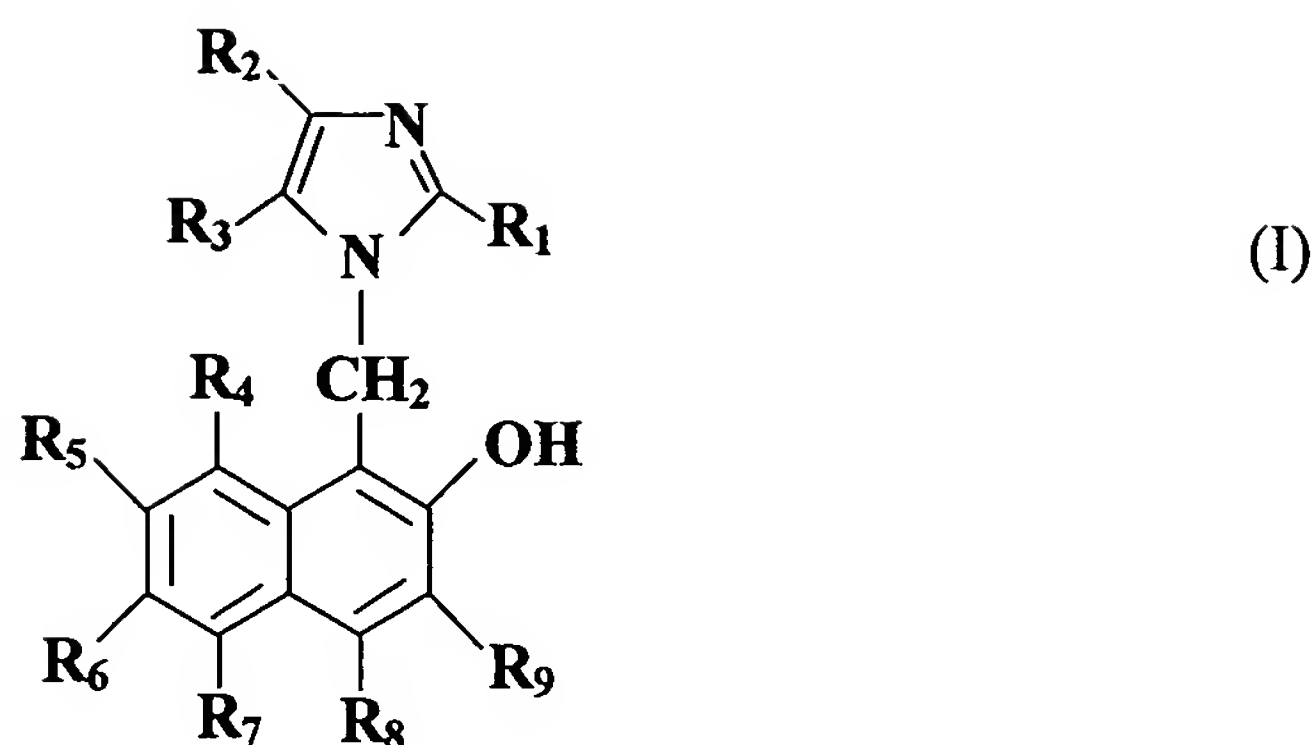
Claim 9 (currently amended). Composition according to Claim 8, ~~characterized in that the curing agent is selected from amines, preferably from diamines and polyamines~~ wherein the curing agent is an amine or polyamine.

Claim 10 (currently amended). Composition according to Claim ~~7~~ 9, characterized in that the curing agent is a polyoxypropylenediamine.

Claim 11 (original). Composition according to Claim 8, characterized in that the epoxy resin is a glycidyl ether, glycidyl ester, N-glycidyl or N,O-glycidyl derivative of an aromatic or heterocyclic compound, or a cycloaliphatic glycidyl compound.

Claim 12 (cancelled).

Claim 13 (new). A method for making a curable composition comprising adding to an epoxy resin a curing agent, a 1-imidazolymethyl-substituted 2-naphthol compound of the general formula (I)



where

R₁, R₂, and R₃ each independently of one another are H; C₁₋₁₇ alkyl; C₃₋₁₂ cycloalkyl, optionally substituted by C₁₋₄ alkyl groups; C₄₋₂₀ cycloalkyl-alkyl, optionally substituted by C₁₋₄ alkyl groups; C₆₋₁₀ aryl, optionally substituted by 1-3 C₁₋₄ alkyl groups; C₇₋₁₅ phenylalkyl, optionally substituted by 1-3 C₁₋₄ alkyl groups; C₃₋₁₇ alkenyl; C₃₋₁₂ alkynyl; or aromatic or aliphatic C₃₋₁₂ acyl;

R₄, R₅, R₆, R₇, R₈ and R₉ each independently of one another are H; C₁₋₁₂ alkyl; C₃₋₁₂ cycloalkyl, optionally substituted by C₁₋₄ alkyl groups; C₄₋₂₀ cycloalkyl-alkyl, optionally substituted by C₁₋₄ alkyl groups; C₆₋₁₀ aryl, optionally substituted by 1-3 C₁₋₄ alkyl groups; C₇₋₁₅ phenylalkyl, optionally substituted by 1-3 C₁₋₄ alkyl groups; C₃₋₁₇ alkenyl; C₃₋₁₂ alkynyl; C₁₋₁₂ alkoxy; or OH; and

a phenol which is liquid at room temperature, the weight ratio of the 1-imidazolylmethyl-substituted 2-naphthol compound to phenol being from 10:90 to 80:20.

Claim 14 (new). The method of claim 13 wherein the 1-imidazolylmethyl-substituted 2-naphthol compound of formula (I) and the phenol are dissolved beforehand in the curing agent at a temperature between 60° - 80° C.

Claim 15 (new). A prepreg comprising a curable composition according to Claim 8.